ICERA TO ACQUIRE SIRIFIC WIRELESS FOR RADIO FREQUENCY (RF) CMOS TECHNOLOGY
Strengthens Icera’s competitive position in the wireless chipset market

Bristol, UK, 7 April 2008. Icera Inc., the leader in software defined wireless modem chipsets, today announced that it has signed a definitive agreement to merge with Sirific Wireless, a fabless semiconductor company specializing in advanced CMOS RF transceivers. This will enable Icera to deliver a complete chipset solution for the mobile broadband market, which industry analysts expect to grow from just 90 million subscribers today to 1.3 billion by 2012.

The deal significantly accelerates Icera’s time to market and competitive position for complete wireless modem chipsets used in mobile broadband datacards, USB dongles, laptops, mobile internet devices and mobile phones.

Stan Boland, President and CEO of Icera, said: “Sirific has industry leading CMOS RF expertise which greatly complements Icera’s category-defining soft baseband technology. The merger of the two companies enables Icera to deliver all of the complex modem silicon to manufacturers of cellular data devices and phones, strengthening our emerging position as a tier 1 supplier in the mobile broadband market.”

Tajinder Manku, Founder and CTO of Sirific Wireless said: “We are excited by the opportunity to combine our resources with those of the Icera team to create an industry-leading wireless modem chipset company.”

Sirific’s range of advanced single-chip, multi-band, multi-mode (HSDPA, HSUPA, WCDMA, EDGE, GPRS, GSM) CMOS RF transceivers integrate advanced direct up-/down-conversion architectures, a patented frequency synthesizer, a dual-receive path to support receive diversity and a DigRF-compliant baseband interface to increase functionality, while reducing cost, size and power consumption.

Icera’s Livanto® is the world’s first software baseband for mobile phones and cellular data devices. A new type of processor - DXP® in Livanto®, allows all the wireless modem functions to be implemented in a software modem called Adaptive Wireless™. Icera is the only company able to achieve this completely soft solution shipping today in commercial devices.
Livanto® delivers the world’s highest performance HSPA solution, enabling consumers to send and receive large email files with attachments, speedily access web pages and download music tracks over the air in seconds. Already supporting 2.5G standards, GSM, GPRS and EDGE as well as the highest performance 3G (WCDMA, HSDPA, HSUPA), Livanto® will be developed for additional air interfaces, including HSPA+ and LTE which can be consolidated as a multimode solution on the same device.

The existing Sirific design locations in Richardson, Texas, USA and Waterloo, Canada will be retained. These locations will continue to focus on leading edge CMOS RF silicon and system design. This will bring the total number of design locations for the combined company to five and the total number of employees to 260.

The boards of directors of each of the companies have approved the merger. The closing, which is expected to occur in Q2 2008, remains subject to customary closing conditions. The financial terms of the deal have not been disclosed. The merged companies will use the Icera name.

About Icera
Icera is a fabless semiconductor company, pioneering high performance, low power, software defined wireless modem chipsets for the fast growing mobile broadband device market. Icera technology delivers the highest performance modem solutions for USB dongles, datacards, laptops, mobile internet devices and mobile phones. Founded in 2002, Icera is headquartered in the UK, with design locations in Bristol and Cambridge, UK and Sophia Antipolis, France, with sales offices in Europe, Japan, Taiwan and USA. For more information, visit the Icera web site at www.icerasemi.com

About Sirific Wireless
Sirific Wireless Limited is a privately held fabless semiconductor company that designs and develops CMOS RF transceiver integrated circuits for multi-mode mobile devices. Sirific is Advancing RF CMOS™ with a portfolio of single-chip 3.5G products that exceed today’s industry standards to satisfy the requirements of tomorrow’s wireless applications. The company is headquartered in Richardson, Texas, with design facilities in Richardson, Texas, Waterloo, Ontario Canada. For more information about Sirific Wireless visit http://www.sirific.com.

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